



Council of the
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COVER NOTE

From: Secretary-General of the European Commission,
signed by Mr Jordi AYET PUIGARNAU, Director

date of receipt: 19 November 2018

To: Mr Jeppe TRANHOLM-MIKKELSEN, Secretary-General of the Council of
the European Union

No. Cion doc.: C(2018) 7499 final - Annex

Subject: ANNEX to the Commission Delegated Directive amending, for the
purposes of adapting to technical progress, Annex III to Directive
2011/65/EU of the European Parliament and of the Council as regards an
exemption for lead in solders to complete a viable electrical connection
between semiconductor die and carrier within integrated circuit flip chip
packages

Delegations will find attached document C(2018) 7499 final - Annex.

Encl.: C(2018) 7499 final - Annex



Brussels, 16.11.2018
C(2018) 7499 final

ANNEX

ANNEX

to

Commission Delegated Directive

amending, for the purposes of adapting to technical progress, Annex III to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

ANNEX

In Annex III, entry 15 is replaced by the following:

| | | |
|-------|---|--|
| "15 | Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages | Applies to categories 8, 9 and 11 and expires on: <ul style="list-style-type: none">– 21 July 2021 for categories 8 and 9 other than in vitro diagnostic medical devices and industrial monitoring and control instruments;– 21 July 2023 for category 8 in vitro diagnostic medical devices;– 21 July 2024 for category 9 industrial monitoring and control instruments, and for category 11. |
| 15(a) | Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: <ul style="list-style-type: none">– a semiconductor technology node of 90 nm or larger;– a single die of 300 mm² or larger in any semiconductor technology node;– stacked die packages with die of 300 mm² or larger, or silicon interposers of 300 mm² or larger. | Applies to categories 1 to 7 and 10 and expires on 21 July 2021." |